



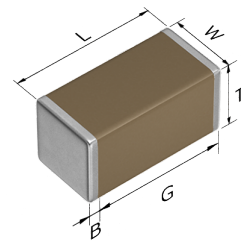


交货型号	C3216X7R2J223KT5***
用途	 一般等级
特点	 中耐压 (100~630V)  开路模式
系列	C3216 [EIA 1206]
状态	 量产体制(新设计非推荐)



尺寸

长度(L)	3.20mm ±0.20mm
宽度(W)	1.60mm ±0.20mm
厚度(T)	1.30mm ±0.20mm
端子宽度(B)	0.20mm Min.
端子间隔(G)	1.00mm Min.
推荐焊盘布局(PA)	2.10mm to 2.50mm(Flow Soldering) 2.00mm to 2.40mm(Reflow Soldering)
推荐焊盘布局(PB)	1.10mm to 1.30mm(Flow Soldering) 1.00mm to 1.20mm(Reflow Soldering)
推荐焊盘布局(PC)	1.00mm to 1.30mm(Flow Soldering) 1.10mm to 1.60mm(Reflow Soldering)

电气特性

电容	22nF ±10%
额定电压	630VDC
温度特性	X7R(±15%)
耗散因数 (Max.)	3%
绝缘电阻 (Min.)	10000MΩ

其他

焊接方法	流体 回流
AEC-Q200	NO
包装形式	塑封编带 (180mm卷筒)
包装个数	2000pcs

! Images are for reference only and show exemplary products.

! This PDF document was created based on the data listed on the TDK Corporation website.

! All specifications are subject to change without notice.

积层贴片陶瓷片式电容器

C3216X7R2J223K130AM

RoHS Reach Halogen Free Pb Free

特性图表 (这是参考数据，并不保证产品的特性。)

Associated Images

